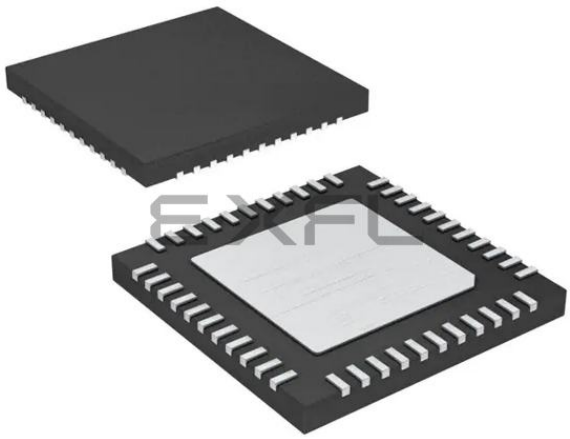

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Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	64MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	35
Program Memory Size	32KB (16K x 16)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	1.5K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 5.5V
Data Converters	A/D 30x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f45k22t-i-ml

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  - Supports RS-485, RS-232 and LIN
  - RS-232 operation using internal oscillator
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TABLE 1: PIC18(L)F2X/4XK22 FAMILY TYPES

Device	Program Memory		Data Memory		I/O(1)	10-bit A/D Channels(2)	CCP	ECCP (Full-Bridge)	ECCP (Half-Bridge)	MSSP		EUSART	Comparator	CTMU	BOR/LVD	SR Latch	8-bit Timer	16-bit Timer
	Flash (Bytes)	# Single-Word Instructions	SRAM (Bytes)	EEPROM (Bytes)						SPI	I^2C							
PIC18(L)F23K22	8K	4096	512	256	25	19	2	1	2	2	2	2	2	Y	Y	Y	3	4
PIC18(L)F24K22	16K	8192	768	256	25	19	2	1	2	2	2	2	2	Y	Y	Y	3	4
PIC18(L)F25K22	32K	16384	1536	256	25	19	2	1	2	2	2	2	2	Y	Y	Y	3	4
PIC18(L)F26K22	64k	32768	3896	1024	25	19	2	1	2	2	2	2	2	Y	Y	Y	3	4
PIC18(L)F43K22	8K	4096	512	256	36	30	2	2	1	2	2	2	2	Y	Y	Y	3	4
PIC18(L)F44K22	16K	8192	768	256	36	30	2	2	1	2	2	2	2	Y	Y	Y	3	4
PIC18(L)F45K22	32K	16384	1536	256	36	30	2	2	1	2	2	2	2	Y	Y	Y	3	4
PIC18(L)F46K22	64k	32768	3896	1024	36	30	2	2	1	2	2	2	2	Y	Y	Y	3	4

Note 1: One pin is input only.

2: Channel count includes internal FVR and DAC channels.

2.5.3 LP, XT, HS MODES

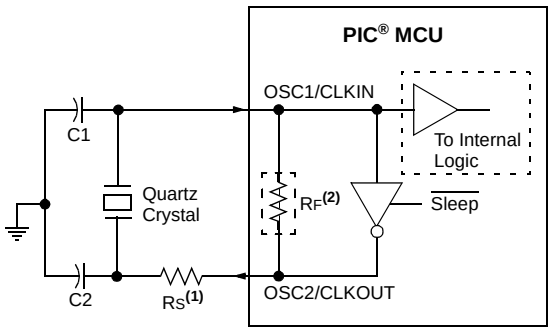
The LP, XT and HS modes support the use of quartz crystal resonators or ceramic resonators connected to OSC1 and OSC2 (Figure 2-6). The mode selects a low, medium or high gain setting of the internal inverter-amplifier to support various resonator types and speed.

LP Oscillator mode selects the lowest gain setting of the internal inverter-amplifier. LP mode current consumption is the least of the three modes. This mode is best suited to drive resonators with a low drive level specification, for example, tuning fork type crystals.

XT Oscillator mode selects the intermediate gain setting of the internal inverter-amplifier. XT mode current consumption is the medium of the three modes. This mode is best suited to drive resonators with a medium drive level specification.

HS Oscillator mode offers a Medium Power (MP) and a High Power (HP) option selectable by the FOSC<3:0> bits. The MP selections are best suited for oscillator frequencies between 4 MHz and 16 MHz. The HP selection has the highest gain setting of the internal inverter-amplifier and is best suited for frequencies above 16 MHz. HS mode is best suited for resonators that require a high drive setting.

FIGURE 2-6: QUARTZ CRYSTAL OPERATION (LP, XT OR HS MODE)



Note 1: A series resistor (RS) may be required for quartz crystals with low drive level.

2: The value of RF varies with the Oscillator mode selected (typically between 2 MΩ to 10 MΩ).

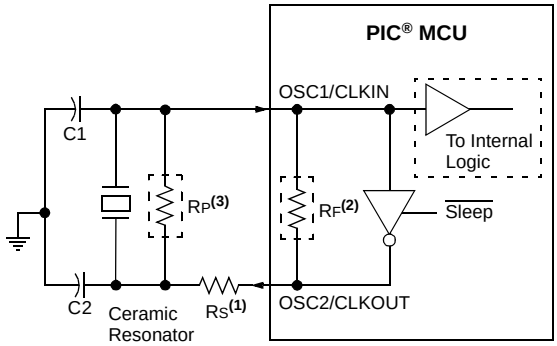
Note 1: Quartz crystal characteristics vary according to type, package and manufacturer. The user should consult the manufacturer data sheets for specifications and recommended application.

2: Always verify oscillator performance over the VDD and temperature range that is expected for the application.

3: For oscillator design assistance, refer to the following Microchip Application Notes:

- AN826, "*Crystal Oscillator Basics and Crystal Selection for rfPIC® and PIC® Devices*" (DS00826)
- AN849, "*Basic PIC® Oscillator Design*" (DS00849)
- AN943, "*Practical PIC® Oscillator Analysis and Design*" (DS00943)
- AN949, "*Making Your Oscillator Work*" (DS00949)

FIGURE 2-7: CERAMIC RESONATOR OPERATION (XT OR HS MODE)

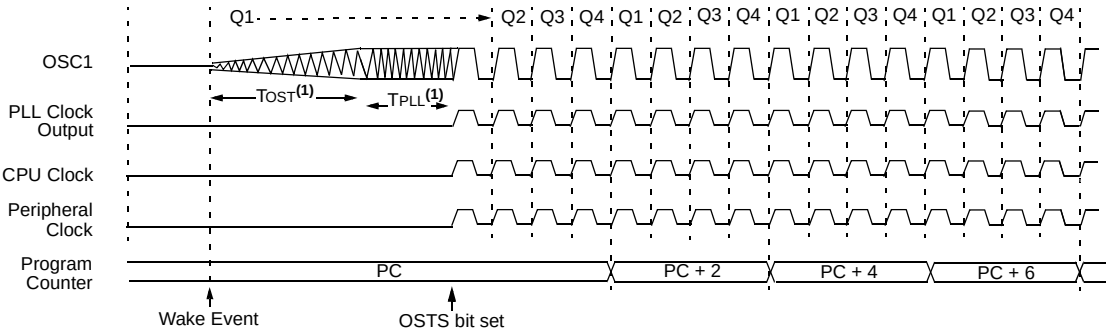


Note 1: A series resistor (RS) may be required for ceramic resonators with low drive level.

2: The value of RF varies with the Oscillator mode selected (typically between 2 MΩ to 10 MΩ).

3: An additional parallel feedback resistor (RP) may be required for proper ceramic resonator operation.

FIGURE 3-5: TRANSITION TIMING FOR WAKE FROM SLEEP (HSPLL)



Note 1: TOST = 1024 TOSC; TPLL = 2 ms (approx). These intervals are not shown to scale.

3.4.1 PRI_IDLE MODE

This mode is unique among the three low-power Idle modes, in that it does not disable the primary device clock. For timing sensitive applications, this allows for the fastest resumption of device operation with its more accurate primary clock source, since the clock source does not have to “warm-up” or transition from another oscillator.

PRI_IDLE mode is entered from PRI_RUN mode by setting the IDLEN bit and executing a SLEEP instruction. If the device is in another Run mode, set IDLEN first, then clear the SCS bits and execute SLEEP. Although the CPU is disabled, the peripherals continue to be clocked from the primary clock source specified by the FOSC<3:0> Configuration bits. The OSTS bit remains set (see Figure 3-6).

When a wake event occurs, the CPU is clocked from the primary clock source. A delay of interval TCSD is required between the wake event and when code execution starts. This is required to allow the CPU to become ready to execute instructions. After the wake-up, the OSTS bit remains set. The IDLEN and SCS bits are not affected by the wake-up (see Figure 3-7).

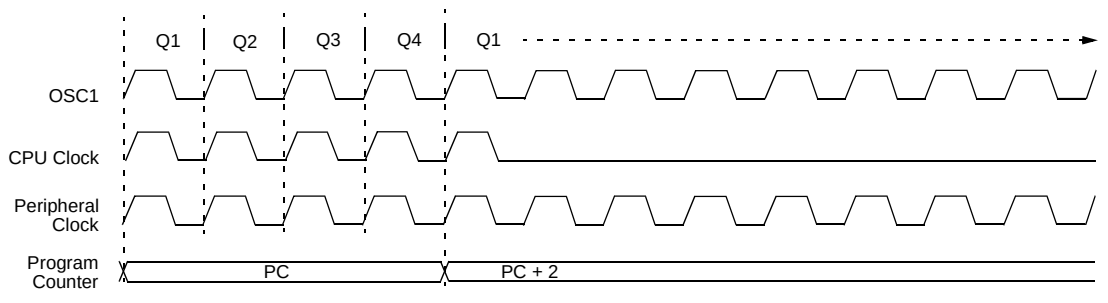
3.4.2 SEC_IDLE MODE

In SEC_IDLE mode, the CPU is disabled but the peripherals continue to be clocked from the SOSC oscillator. This mode is entered from SEC_RUN by setting the IDLEN bit and executing a SLEEP instruction. If the device is in another Run mode, set the IDLEN bit first, then set the SCS<1:0> bits to ‘01’ and execute SLEEP. When the clock source is switched to the SOSC oscillator, the primary oscillator is shut down, the OSTS bit is cleared and the SOSCRUN bit is set.

When a wake event occurs, the peripherals continue to be clocked from the SOSC oscillator. After an interval of TCSD following the wake event, the CPU begins executing code being clocked by the SOSC oscillator. The IDLEN and SCS bits are not affected by the wake-up; the SOSC oscillator continues to run (see Figure 3-7).

Note:	The SOSC oscillator should already be running prior to entering SEC_IDLE mode. At least one of the secondary oscillator enable bits (SOSCGO, T1SOSCEN, T3SOSCEN or T5SOSCEN) must be set when the SLEEP instruction is executed. Otherwise, the main system clock will continue to operate in the previously selected mode and the corresponding IDLE mode will be entered (i.e., PRI_IDLE or RC_IDLE).

FIGURE 3-6: TRANSITION TIMING FOR ENTRY TO IDLE MODE



4.5 Brown-out Reset (BOR)

PIC18(L)F2X/4XK22 devices implement a BOR circuit that provides the user with a number of configuration and power-saving options. The BOR is controlled by the BORV<1:0> and BOREN<1:0> bits of the CONFIG2L Configuration register. There are a total of four BOR configurations which are summarized in Table 4-1.

The BOR threshold is set by the BORV<1:0> bits. If BOR is enabled (any values of BOREN<1:0>, except '00'), any drop of V_{DD} below V_{BOR} for greater than T_{BOR} will reset the device. A Reset may or may not occur if V_{DD} falls below V_{BOR} for less than T_{BOR}. The chip will remain in Brown-out Reset until V_{DD} rises above V_{BOR}.

If the Power-up Timer is enabled, it will be invoked after V_{DD} rises above V_{BOR}; it then will keep the chip in Reset for an additional time delay, T_{PWRT}. If V_{DD} drops below V_{BOR} while the Power-up Timer is running, the chip will go back into a Brown-out Reset and the Power-up Timer will be initialized. Once V_{DD} rises above V_{BOR}, the Power-up Timer will execute the additional time delay.

BOR and the Power-on Timer (PWRT) are independently configured. Enabling BOR Reset does not automatically enable the PWRT.

The BOR circuit has an output that feeds into the POR circuit and rearms the POR within the operating range of the BOR. This early rearming of the POR ensures that the device will remain in Reset in the event that V_{DD} falls below the operating range of the BOR circuitry.

4.5.1 DETECTING BOR

When BOR is enabled, the $\overline{BOR}$ bit always resets to '0' on any BOR or POR event. This makes it difficult to determine if a BOR event has occurred just by reading the state of $\overline{BOR}$ alone. A more reliable method is to simultaneously check the state of both $\overline{POR}$ and $\overline{BOR}$. This assumes that the $\overline{POR}$ and $\overline{BOR}$ bits are reset to '1' by software immediately after any POR event. If $\overline{BOR}$ is '0' while $\overline{POR}$ is '1', it can be reliably assumed that a BOR event has occurred.

4.5.2 SOFTWARE ENABLED BOR

When BOREN<1:0> = 01, the BOR can be enabled or disabled by the user in software. This is done with the SBOREN control bit of the RCON register. Setting SBOREN enables the BOR to function as previously described. Clearing SBOREN disables the BOR entirely. The SBOREN bit operates only in this mode; otherwise it is read as '0'.

Placing the BOR under software control gives the user the additional flexibility of tailoring the application to the environment without having to reprogram the device to change BOR configuration. It also allows the user to tailor device power consumption in software by eliminating the incremental current that the BOR consumes. While the BOR current is typically very small, it may have some impact in low-power applications.

Note:	Even when BOR is under software control, the BOR Reset voltage level is still set by the BORV<1:0> Configuration bits. It cannot be changed by software.

4.5.3 DISABLING BOR IN SLEEP MODE

When BOREN<1:0> = 10, the BOR remains under hardware control and operates as previously described. Whenever the device enters Sleep mode, however, the BOR is automatically disabled. When the device returns to any other operating mode, BOR is automatically re-enabled.

This mode allows for applications to recover from brown-out situations, while actively executing code, when the device requires BOR protection the most. At the same time, it saves additional power in Sleep mode by eliminating the small incremental BOR current.

4.5.4 MINIMUM BOR ENABLE TIME

Enabling the BOR also enables the Fixed Voltage Reference (FVR) when no other peripheral requiring the FVR is active. The BOR becomes active only after the FVR stabilizes. Therefore, to ensure BOR protection, the FVR settling time must be considered when enabling the BOR in software or when the BOR is automatically enabled after waking from Sleep. If the BOR is disabled, in software or by reentering Sleep before the FVR stabilizes, the BOR circuit will not sense a BOR condition. The FVRST bit of the VREFCON0 register can be used to determine FVR stability.

REGISTER 9-5: PIR2: PERIPHERAL INTERRUPT REQUEST (FLAG) REGISTER 2

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
OSCFIF	C1IF	C2IF	EEIF	BCL1IF	HLVDIF	TMR3IF	CCP2IF
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **OSCFIF:** Oscillator Fail Interrupt Flag bit
1 = Device oscillator failed, clock input has changed to HFINTOSC (must be cleared by software)
0 = Device clock operating

bit 6 **C1IF:** Comparator C1 Interrupt Flag bit
1 = Comparator C1 output has changed (must be cleared by software)
0 = Comparator C1 output has not changed

bit 5 **C2IF:** Comparator C2 Interrupt Flag bit
1 = Comparator C2 output has changed (must be cleared by software)
0 = Comparator C2 output has not changed

bit 4 **EEIF:** Data EEPROM/Flash Write Operation Interrupt Flag bit
1 = The write operation is complete (must be cleared by software)
0 = The write operation is not complete or has not been started

bit 3 **BCL1IF:** MSSP1 Bus Collision Interrupt Flag bit
1 = A bus collision occurred (must be cleared by software)
0 = No bus collision occurred

bit 2 **HLVDIF:** Low-Voltage Detect Interrupt Flag bit
1 = A low-voltage condition occurred (direction determined by the VDIRMAG bit of the HLVDCON register)
0 = A low-voltage condition has not occurred

bit 1 **TMR3IF:** TMR3 Overflow Interrupt Flag bit
1 = TMR3 register overflowed (must be cleared by software)
0 = TMR3 register did not overflow

bit 0 **CCP2IF:** CCP2 Interrupt Flag bit

Capture mode:
1 = A TMR register capture occurred (must be cleared by software)
0 = No TMR register capture occurred

Compare mode:
1 = A TMR register compare match occurred (must be cleared by software)
0 = No TMR register compare match occurred

PWM mode:
Unused in this mode.

REGISTER 9-8: PIR5: PERIPHERAL INTERRUPT (FLAG) REGISTER 5

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	—	—	—	—	TMR6IF	TMR5IF	TMR4IF
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-3 **Unimplemented:** Read as '0'

bit 2 **TMR6IF:** TMR6 to PR6 Match Interrupt Flag bit
1 = TMR6 to PR6 match occurred (must be cleared in software)
0 = No TMR6 to PR6 match occurred

bit 1 **TMR5IF:** TMR5 Overflow Interrupt Flag bit
1 = TMR5 register overflowed (must be cleared in software)
0 = TMR5 register did not overflow

bit 0 **TMR4IF:** TMR4 to PR4 Match Interrupt Flag bit
1 = TMR4 to PR4 match occurred (must be cleared in software)
0 = No TMR4 to PR4 match occurred

REGISTER 9-14: IPR1: PERIPHERAL INTERRUPT PRIORITY REGISTER 1

U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	ADIP	RC1IP	TX1IP	SSP1IP	CCP1IP	TMR2IP	TMR1IP
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7 **Unimplemented:** Read as ‘0’

bit 6 **ADIP:** A/D Converter Interrupt Priority bit
1 = High priority
0 = Low priority

bit 5 **RC1IP:** EUSART1 Receive Interrupt Priority bit
1 = High priority
0 = Low priority

bit 4 **TX1IP:** EUSART1 Transmit Interrupt Priority bit
1 = High priority
0 = Low priority

bit 3 **SSP1IP:** Master Synchronous Serial Port 1 Interrupt Priority bit
1 = High priority
0 = Low priority

bit 2 **CCP1IP:** CCP1 Interrupt Priority bit
1 = High priority
0 = Low priority

bit 1 **TMR2IP:** TMR2 to PR2 Match Interrupt Priority bit
1 = High priority
0 = Low priority

bit 0 **TMR1IP:** TMR1 Overflow Interrupt Priority bit
1 = High priority
0 = Low priority

10.4 PORTC Registers

PORTC is an 8-bit wide, bidirectional port. The corresponding data direction register is TRISC. Setting a TRISC bit (= 1) will make the corresponding PORTC pin an input (i.e., disable the output driver). Clearing a TRISC bit (= 0) will make the corresponding PORTC pin an output (i.e., enable the output driver and put the contents of the output latch on the selected pin).

The Data Latch register (LATC) is also memory mapped. Read-modify-write operations on the LATC register read and write the latched output value for PORTC.

PORTC is multiplexed with several peripheral functions (Table 10-8). The pins have Schmitt Trigger input buffers.

Some of these pin functions can be relocated to alternate pins using the Control fuse bits in CONFIG3H. RC0 is the default pin for T3CKI. Clearing the T3CMX bit moves the pin function to RB5. RC1 is the default pin for the CCP2 peripheral pin. Clearing the CCP2MX bit moves the pin function to the RB3 pin.

Two other pin functions, P2B and CCP3, can be relocated from their default pins to PORTC pins by clearing the control fuses in CONFIG3H. Clearing P2BMX and CCP3MX moves the pin functions to RC0 and RC6**(1)**/RE0**(2)**, respectively.

When enabling peripheral functions, care should be taken in defining TRIS bits for each PORTC pin. The EUSART and MSSP peripherals override the TRIS bit to make a pin an output or an input, depending on the peripheral configuration. Refer to the corresponding peripheral section for additional information.

Note:	On a Power-on Reset, these pins are configured as analog inputs.

The contents of the TRISC register are affected by peripheral overrides. Reading TRISC always returns the current contents, even though a peripheral device may be overriding one or more of the pins.

EXAMPLE 10-3: INITIALIZING PORTC

```
MOVLB   0xF     ; Set BSR for banked SFRs
CLRF    PORTC   ; Initialize PORTC by
                ; clearing output
                ; data latches
CLRF    LATC    ; Alternate method
                ; to clear output
                ; data latches
MOVLW   0CFh    ; Value used to
                ; initialize data
                ; direction
MOVWF   TRISC   ; Set RC<3:0> as inputs
                ; RC<5:4> as outputs
                ; RC<7:6> as inputs
MOVLW   30h     ; Value used to
                ; enable digital inputs
MOVWF   ANSELC  ; RC<3:2> dig input enable
                ; No ANSEL bits for RC<1:0>
                ; RC<7:6> dig input enable
```

10.4.1 PORTC OUTPUT PRIORITY

Each PORTC pin is multiplexed with other functions. The pins, their combined functions and their output priorities are briefly described here. For additional information, refer to the appropriate section in this data sheet.

When multiple outputs are enabled, the actual pin control goes to the peripheral with the higher priority. Table 10-4 lists the PORTC pin functions from the highest to the lowest priority.

Analog input functions, such as ADC, comparator and SR latch inputs, are not shown in the priority lists.

These inputs are active when the I/O pin is set for Analog mode using the ANSELx registers. Digital output functions may control the pin when it is in Analog mode with the priority shown below.

10.5 PORTD Registers

Note: PORTD is only available on 40-pin and 44-pin devices.

PORTD is an 8-bit wide, bidirectional port. The corresponding data direction register is TRISD. Setting a TRISD bit (= 1) will make the corresponding PORTD pin an input (i.e., disable the output driver). Clearing a TRISD bit (= 0) will make the corresponding PORTD pin an output (i.e., enable the output driver and put the contents of the output latch on the selected pin).

The Data Latch register (LATD) is also memory mapped. Read-modify-write operations on the LATD register read and write the latched output value for PORTD.

All pins on PORTD are implemented with Schmitt Trigger input buffers. Each pin is individually configurable as an input or output.

All of the PORTD pins are multiplexed with analog and digital peripheral modules. See Table 10-11.

Note: On a Power-on Reset, these pins are configured as analog inputs.

EXAMPLE 10-4: INITIALIZING PORTD

```
MOVLB   0xF     ; Set BSR for banked SFRs
CLRF    PORTD   ; Initialize PORTD by
                ; clearing output
                ; data latches
CLRF    LATD    ; Alternate method
                ; to clear output
                ; data latches
MOVLW   0CFh    ; Value used to
                ; initialize data
                ; direction
MOVWF   TRISD   ; Set RD<3:0> as inputs
                ; RD<5:4> as outputs
                ; RD<7:6> as inputs
MOVLW   30h     ; Value used to
                ; enable digital inputs
MOVWF   ANSELD  ; RD<3:0> dig input enable
                ; RC<7:6> dig input enable
```

10.5.1 PORTD OUTPUT PRIORITY

Each PORTD pin is multiplexed with other functions. The pins, their combined functions and their output priorities are briefly described here. For additional information, refer to the appropriate section in this data sheet.

When multiple outputs are enabled, the actual pin control goes to the peripheral with the higher priority. Table 10-4 lists the PORTD pin functions from the highest to the lowest priority.

Analog input functions, such as ADC, comparator and SR latch inputs, are not shown in the priority lists.

These inputs are active when the I/O pin is set for Analog mode using the ANSELx registers. Digital output functions may control the pin when it is in Analog mode with the priority shown below.

REGISTER 10-10: LATx: PORTx OUTPUT LATCH REGISTER(1)

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
LATx7	LATx6	LATx5	LATx4	LATx3	LATx2	LATx1	LATx0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 **LATx<7:0>:** PORTx Output Latch bit value(2)

Note 1: Register Description for LATA, LATB, LATC and LATD.

2: Writes to PORTx are written to corresponding LATx register. Reads from PORTx register is return of I/O pin values.

REGISTER 10-11: LATE: PORTE OUTPUT LATCH REGISTER(1)

U-0	U-0	U-0	U-0	U-0	R/W-x/u	R/W-x/u	R/W-x/u
—	—	—	—	—	LATE2	LATE1	LATE0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-3 **Unimplemented:** Read as '0'

bit 2-0 **LATE<2:0>:** PORTE Output Latch bit value(2)

Note 1: Available on PIC18(L)F4XK22 devices only.

2: Writes to PORTE are written to corresponding LATE register. Reads from PORTE register is return of I/O pin values.

REGISTER 10-12: WPUB: WEAK PULL-UP PORTB REGISTER

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
WPUB7	WPUB6	WPUB5	WPUB4	WPUB3	WPUB2	WPUB1	WPUB0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 **WPUB<7:0>:** Weak Pull-up Register bits

1 = Pull-up enabled on PORT pin

0 = Pull-up disabled on PORT pin

REGISTER 12-2: TXGCON: TIMER1/3/5 GATE CONTROL REGISTER

R/W-0/u	R/W-0/u	R/W-0/u	R/W-0/u	R/W/HC-0/u	R-x/x	R/W-0/u	R/W-0/u
TMRxGE	TxGPOL	TxGTM	TxGSPM	TxGGO/$\overline{\text{DONE}}$	TxGVAL	TxGSS<1:0>	
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	HC = Bit is cleared by hardware

bit 7 **TMRxGE:** Timer1/3/5 Gate Enable bit
If TMRxON = 0:
This bit is ignored
If TMRxON = 1:
1 = Timer1/3/5 counting is controlled by the Timer1/3/5 gate function
0 = Timer1/3/5 counts regardless of Timer1/3/5 gate function

bit 6 **TxGPOL:** Timer1/3/5 Gate Polarity bit
1 = Timer1/3/5 gate is active-high (Timer1/3/5 counts when gate is high)
0 = Timer1/3/5 gate is active-low (Timer1/3/5 counts when gate is low)

bit 5 **TxGTM:** Timer1/3/5 Gate Toggle Mode bit
1 = Timer1/3/5 Gate Toggle mode is enabled
0 = Timer1/3/5 Gate Toggle mode is disabled and toggle flip-flop is cleared
Timer1/3/5 gate flip-flop toggles on every rising edge.

bit 4 **TxGSPM:** Timer1/3/5 Gate Single-Pulse Mode bit
1 = Timer1/3/5 gate Single-Pulse mode is enabled and is controlling Timer1/3/5 gate
0 = Timer1/3/5 gate Single-Pulse mode is disabled

bit 3 **TxGGO/$\overline{\text{DONE}}$:** Timer1/3/5 Gate Single-Pulse Acquisition Status bit
1 = Timer1/3/5 gate single-pulse acquisition is ready, waiting for an edge
0 = Timer1/3/5 gate single-pulse acquisition has completed or has not been started
This bit is automatically cleared when TxGSPM is cleared.

bit 2 **TxGVAL:** Timer1/3/5 Gate Current State bit
Indicates the current state of the Timer1/3/5 gate that could be provided to TMRxH:TMRxL.
Unaffected by Timer1/3/5 Gate Enable (TMRxGE).

bit 1-0 **TxGSS<1:0>:** Timer1/3/5 Gate Source Select bits
00 = Timer1/3/5 Gate pin
01 = Timer2/4/6 Match PR2/4/6 output (See Table 12-5 for proper timer match selection)
10 = Comparator 1 optionally synchronized output (sync_C1OUT)
11 = Comparator 2 optionally synchronized output (sync_C2OUT)

17.1 ADC Configuration

When configuring and using the ADC the following functions must be considered:

- Port configuration
- Channel selection
- ADC voltage reference selection
- ADC conversion clock source
- Interrupt control
- Results formatting

17.1.1 PORT CONFIGURATION

The ANSELx and TRISx registers configure the A/D port pins. Any port pin needed as an analog input should have its corresponding ANSx bit set to disable the digital input buffer and TRISx bit set to disable the digital output driver. If the TRISx bit is cleared, the digital output level (V_{OH} or V_{OL}) will be converted.

The A/D operation is independent of the state of the ANSx bits and the TRIS bits.

Note 1:	When reading the PORT register, all pins with their corresponding ANSx bit set read as cleared (a low level). However, analog conversion of pins configured as digital inputs (ANSx bit cleared and TRISx bit set) will be accurately converted.
2:	Analog levels on any pin with the corresponding ANSx bit cleared may cause the digital input buffer to consume current out of the device's specification limits.
3:	The PBADEN bit in Configuration Register 3H configures PORTB pins to reset as analog or digital pins by controlling how the bits in ANSELB are reset.

17.1.2 CHANNEL SELECTION

The CHS bits of the ADCON0 register determine which channel is connected to the sample and hold circuit.

When changing channels, a delay is required before starting the next conversion. Refer to **Section 17.2 "ADC Operation"** for more information.

17.1.3 ADC VOLTAGE REFERENCE

The PVCFG<1:0> and NVCFG<1:0> bits of the ADCON1 register provide independent control of the positive and negative voltage references.

The positive voltage reference can be:

- V_{DD}
- the fixed voltage reference (FVR BUF2)
- an external voltage source (V_{REF+})

The negative voltage reference can be:

- V_{SS}
- an external voltage source (V_{REF-})

17.1.4 SELECTING AND CONFIGURING ACQUISITION TIME

The ADCON2 register allows the user to select an acquisition time that occurs each time the GO/DONE bit is set.

Acquisition time is set with the ACQT<2:0> bits of the ADCON2 register. Acquisition delays cover a range of 2 to 20 T_{AD}. When the GO/DONE bit is set, the A/D module continues to sample the input for the selected acquisition time, then automatically begins a conversion. Since the acquisition time is programmed, there is no need to wait for an acquisition time between selecting a channel and setting the GO/DONE bit.

Manual acquisition is selected when ACQT<2:0> = `000`. When the GO/DONE bit is set, sampling is stopped and a conversion begins. The user is responsible for ensuring the required acquisition time has passed between selecting the desired input channel and setting the GO/DONE bit. This option is also the default Reset state of the ACQT<2:0> bits and is compatible with devices that do not offer programmable acquisition times.

In either case, when the conversion is completed, the GO/DONE bit is cleared, the ADIF flag is set and the A/D begins sampling the currently selected channel again. When an acquisition time is programmed, there is no indication of when the acquisition time ends and the conversion begins.

17.4 A/D Acquisition Requirements

For the ADC to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The Analog Input model is shown in Figure 17-5. The source impedance (RS) and the internal sampling switch (RSS) impedance directly affect the time required to charge the capacitor CHOLD. The sampling switch (RSS) impedance varies over the device voltage (VDD), see Figure 17-5. The maximum recommended impedance for analog sources is 3 kΩ. As the source impedance is decreased, the acquisition time may be decreased. After the analog input channel is selected (or changed), an A/D acquisition must be done before the conversion can be started. To calculate the minimum acquisition time, Equation 17-1 may be used. This equation assumes that 1/2 LSb error is used (1024 steps for the ADC). The 1/2 LSb error is the maximum error allowed for the ADC to meet its specified resolution.

EQUATION 17-1: ACQUISITION TIME EXAMPLE

Assumptions: $Temperature = 50°C$ *and external impedance of* $10k\Omega$ $3.0V$ V_{DD}

$$T_{ACQ} = \text{Amplifier Settling Time} + \text{Hold Capacitor Charging Time} + \text{Temperature Coefficient}$$
$$= T_{AMP} + T_C + T_{COFF}$$
$$= 5\mu s + T_C + [(\text{Temperature} - 25°C)(0.05\mu s/°C)]$$

The value for T_C *can be approximated with the following equations:*

$$V_{APPLIED}\left(1 - \frac{1}{2047}\right) = V_{CHOLD} \quad ;[1]\ V_{CHOLD}\ \text{charged to within 1/2 lsb}$$

$$V_{APPLIED}\left(1 - e^{\frac{-T_C}{RC}}\right) = V_{CHOLD} \quad ;[2]\ V_{CHOLD}\ \text{charge response to}\ V_{APPLIED}$$

$$V_{APPLIED}\left(1 - e^{\frac{-T_C}{RC}}\right) = V_{APPLIED}\left(1 - \frac{1}{2047}\right) \quad ;\text{combining [1] and [2]}$$

Solving for T_C*:*

$$T_C = -C_{HOLD}(R_{IC} + R_{SS} + R_S)\ ln(1/2047)$$
$$= -13.5pF(1k\Omega + 700\Omega + 10k\Omega)\ ln(0.0004885)$$
$$= 1.20\mu s$$

Therefore:

$$T_{ACQ} = 5\mu s + 1.20\mu s + [(50°C - 25°C)(0.05\mu s/°C)]$$
$$= 7.45\mu s$$

Note 1: The reference voltage (VREF) has no effect on the equation, since it cancels itself out.

2: The charge holding capacitor (CHOLD) is discharged after each conversion.

3: The maximum recommended impedance for analog sources is 10 kΩ. This is required to meet the pin leakage specification.

TABLE 18-2: REGISTERS ASSOCIATED WITH COMPARATOR MODULE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
ANSELA	—	—	ANSA5	—	ANSA3	ANSA2	ANSA1	ANSA0	149
ANSELB	—	—	ANSB5	ANSB4	ANSB3	ANSB2	ANSB1	ANSB0	150
CM2CON1	MC1OUT	MC2OUT	C1RSEL	C2RSEL	C1HYS	C2HYS	C1SYNC	C2SYNC	309
CM1CON0	C1ON	C1OUT	C1OE	C1POL	C1SP	C1R	C1CH<1:0>		308
CM2CON0	C2ON	C2OUT	C2OE	C2POL	C2SP	C2R	C2CH<1:0>		308
VREFCON1	DACEN	DACLPS	DACOE	—	DACPSS<1:0>		—	DACNSS	335
VREFCON2	—	—	—	DACR<4:0>					336
VREFCON0	FVREN	FVRST	FVRS<1:0>		—	—	—	—	332
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	109
IPR2	OSCFIP	C1IP	C2IP	EEIP	BCL1IP	HLVDIP	TMR3IP	CCP2IP	122
PIE2	OSCFIE	C1IE	C2IE	EEIE	BCL1IE	HLVDIE	TMR3IE	CCP2IE	118
PIR2	OSCFIF	C1IF	C2IF	EEIF	BCL1IF	HLVDIF	TMR3IF	CCP2IF	113
PMD2	—	—	—	—	CTMUMD	CMP2MD	CMP1MD	ADCMD	54
TRISA	TRISA7	TRISA6	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	151
TRISB	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	151

Legend: — = unimplemented locations, read as '0'. Shaded bits are not used by the comparator module.

23.0 HIGH/LOW-VOLTAGE DETECT (HLVD)

The PIC18(L)F2X/4XK22 devices have a High/Low-Voltage Detect module (HLVD). This is a programmable circuit that sets both a device voltage trip point and the direction of change from that point. If the device experiences an excursion past the trip point in that direction, an interrupt flag is set. If the interrupt is enabled, the program execution branches to the interrupt vector address and the software responds to the interrupt.

The High/Low-Voltage Detect Control register (Register 23-1) completely controls the operation of the HLVD module. This allows the circuitry to be “turned off” by the user under software control, which minimizes the current consumption for the device.

The module’s block diagram is shown in Figure 23-1.

23.1 Register - HLVD Control

REGISTER 23-1: HLVDCON: HIGH/LOW-VOLTAGE DETECT CONTROL REGISTER

R/W-0	R-0	R-0	R/W-0	R/W-0	R/W-1	R/W-0	R/W-1
VDIRMAG	BGVST	IRVST	HLVDEN	HLVDL<3:0>			
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7 **VDIRMAG:** Voltage Direction Magnitude Select bit
1 = Event occurs when voltage equals or exceeds trip point (HLVDL<3:0>)
0 = Event occurs when voltage equals or falls below trip point (HLVDL<3:0>)

bit 6 **BGVST:** Band Gap Reference Voltages Stable Status Flag bit
1 = Internal band gap voltage references are stable
0 = Internal band gap voltage reference is not stable

bit 5 **IRVST:** Internal Reference Voltage Stable Flag bit
1 = Indicates that the voltage detect logic will generate the interrupt flag at the specified voltage range
0 = Indicates that the voltage detect logic will not generate the interrupt flag at the specified voltage range and the HLVD interrupt should not be enabled

bit 4 **HLVDEN:** High/Low-Voltage Detect Power Enable bit
1 = HLVD enabled
0 = HLVD disabled

bit 3-0 **HLVDL<3:0>:** Voltage Detection Level bits(1)
1111 = External analog input is used (input comes from the HLVDIN pin)
1110 = Maximum setting
.
.
.
0000 = Minimum setting

Note 1: See Table 27-5 for specifications.

CPFSGT **Compare f with W, skip if f > W**

Syntax: CPFSGT f {,a}

Operands: $0 \le f \le 255$
$a \in [0,1]$

Operation: (f) – (W),
skip if (f) > (W)
(unsigned comparison)

Status Affected: None

Encoding:

0110	010a	ffff	ffff

Description: Compares the contents of data memory location 'f' to the contents of the W by performing an unsigned subtraction.
If the contents of 'f' are greater than the contents of WREG, then the fetched instruction is discarded and a NOP is executed instead, making this a 2-cycle instruction.
If 'a' is '0', the Access Bank is selected.
If 'a' is '1', the BSR is used to select the GPR bank.
If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever $f \le 95$ (5Fh). See **Section 25.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1(2)
Note: 3 cycles if skip and followed by a 2-word instruction.

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	No operation

If skip:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation

If skip and followed by 2-word instruction:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation
No operation	No operation	No operation	No operation

Example:
```
HERE      CPFSGT REG, 0
NGREATER  :
GREATER   :
```

Before Instruction
PC = Address (HERE)
W = ?
After Instruction
If REG > W;
PC = Address (GREATER)
If REG ≤ W;
PC = Address (NGREATER)

CPFSLT **Compare f with W, skip if f < W**

Syntax: CPFSLT f {,a}

Operands: $0 \le f \le 255$
$a \in [0,1]$

Operation: (f) – (W),
skip if (f) < (W)
(unsigned comparison)

Status Affected: None

Encoding:

0110	000a	ffff	ffff

Description: Compares the contents of data memory location 'f' to the contents of W by performing an unsigned subtraction.
If the contents of 'f' are less than the contents of W, then the fetched instruction is discarded and a NOP is executed instead, making this a 2-cycle instruction.
If 'a' is '0', the Access Bank is selected.
If 'a' is '1', the BSR is used to select the GPR bank.

Words: 1

Cycles: 1(2)
Note: 3 cycles if skip and followed by a 2-word instruction.

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	No operation

If skip:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation

If skip and followed by 2-word instruction:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation
No operation	No operation	No operation	No operation

Example:
```
HERE    CPFSLT REG, 1
NLESS   :
LESS    :
```

Before Instruction
PC = Address (HERE)
W = ?
After Instruction
If REG < W;
PC = Address (LESS)
If REG ≥ W;
PC = Address (NLESS)

27.7 DC Characteristics: Secondary Oscillator Supply Current, PIC18(L)F2X/4XK22

PIC18LF2X/4XK22		Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C					
PIC18F2X/4XK22		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +125°C					
Param No.	**Device Characteristics**	**Typ**	**Max**	**Units**	**Conditions**		
D135		0.9	18	µA	-40°C	VDD = 1.8V	Fosc = 32 kHz (**SEC_IDLE** mode, SOSC source)
		1.0	18	µA	+25°C		
		1.1	—	µA	+60°C		
		1.3	20	µA	+85°C		
		2.3	22	µA	+125°C		
D136		1.3	20	µA	-40°C	VDD = 3.0V	
		1.4	20	µA	+25°C		
		1.5	—	µA	+60°C		
		1.8	22	µA	+85°C		
		2.9	25	µA	+125°C		
D137		12	30	µA	-40°C	VDD = 2.3V	Fosc = 32 kHz (**SEC_IDLE** mode, SOSC source)
		13	30	µA	+25°C		
		14	30	µA	+85°C		
		16	45	µA	+125°C		
D138		13	35	µA	-40°C	VDD = 3.0V	
		14	35	µA	+25°C		
		16	35	µA	+85°C		
		18	50	µA	+125°C		
D139		14	40	µA	-40°C	VDD = 5.0V	
		15	40	µA	+25°C		
		16	40	µA	+85°C		
		18	60	µA	+125°C		

Note 1: The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.

Test condition: All Peripheral Module Control bits in PMD0, PMD1 and PMD2 set to '1'.

2: The test conditions for all IDD measurements in active operation mode are:

All I/O pins set as outputs driven to Vss;

MCLR = VDD;

SOSCI / SOSCO = complementary external square wave, from rail-to-rail.

FIGURE 28-48: PIC18LF2X/4XK22 TYPICAL IDD: PRI_RUN EC MEDIUM POWER

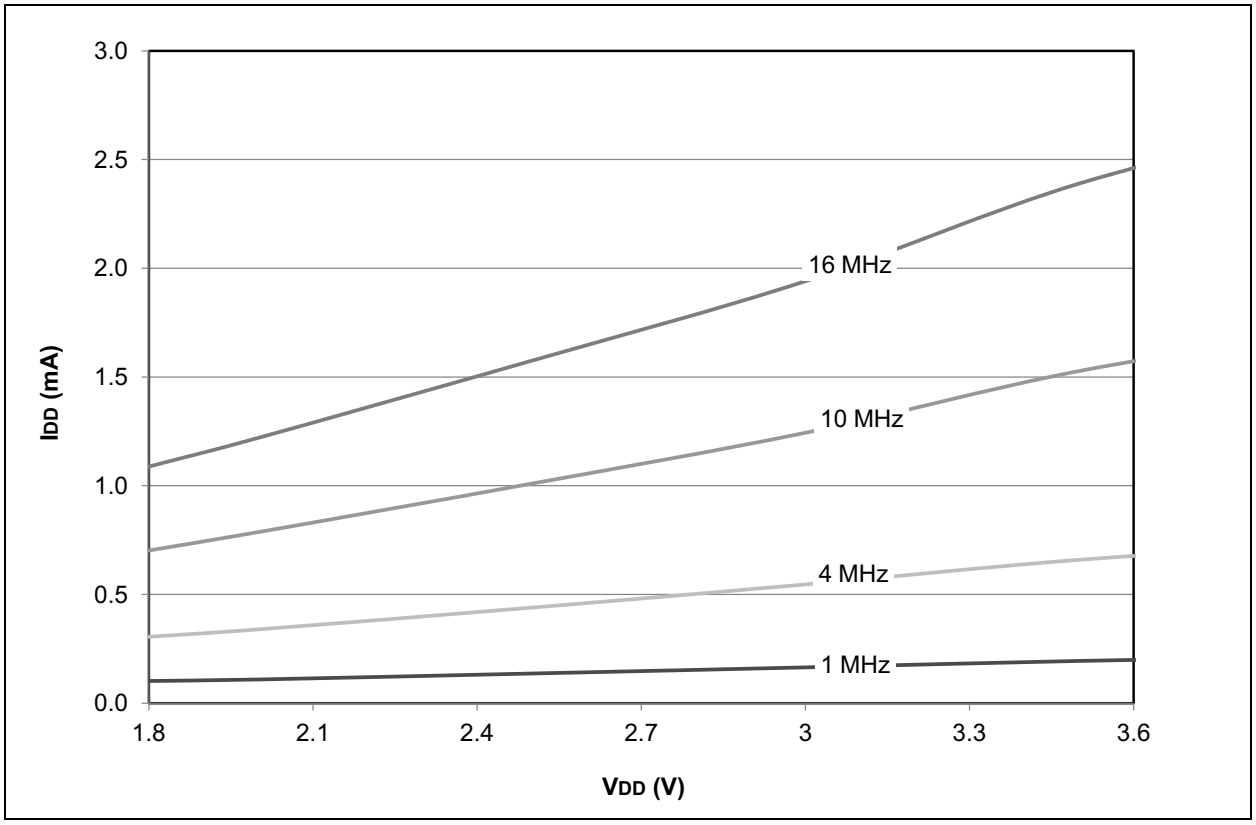


FIGURE 28-49: PIC18LF2X/4XK22 MAXIMUM IDD: PRI_RUN EC MEDIUM POWER

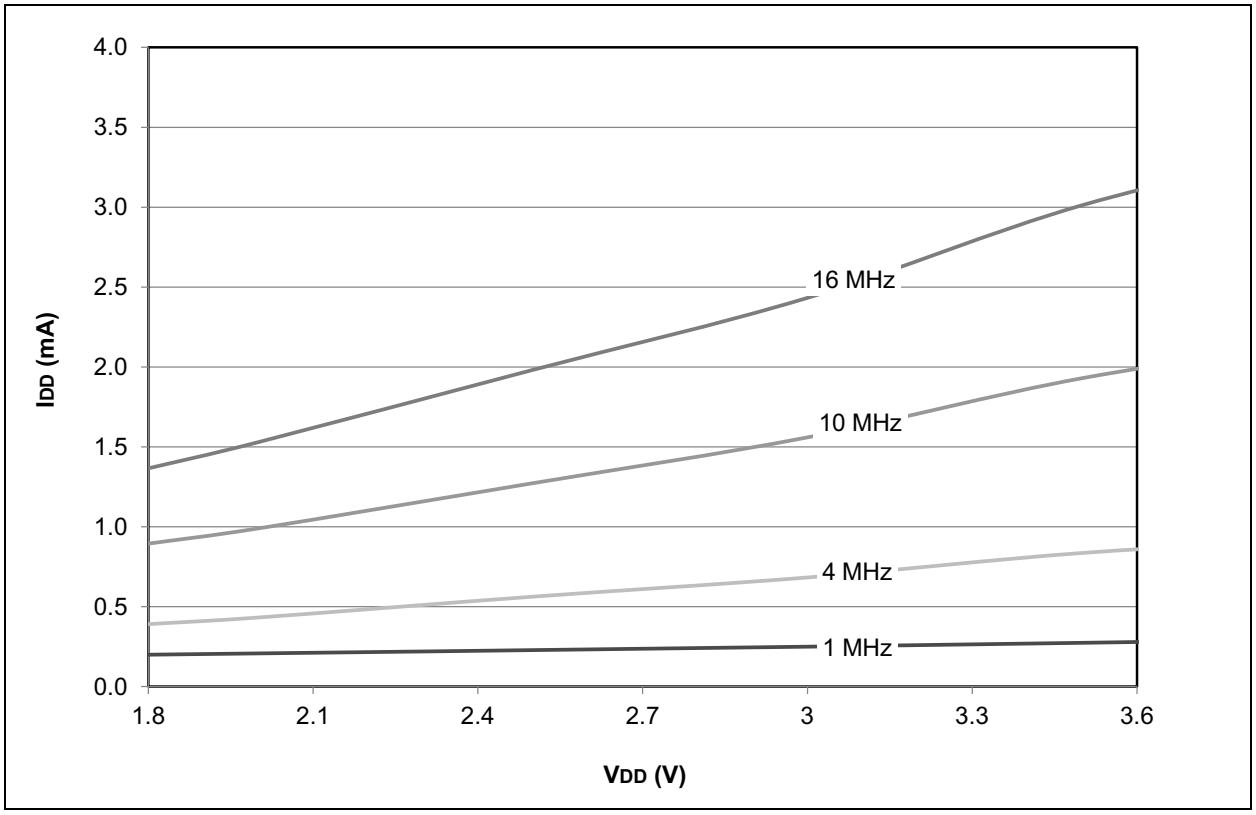


FIGURE 28-96: PIC18(L)F2X/4XK22 TYPICAL FIXED VOLTAGE REFERENCE 2x OUTPUT

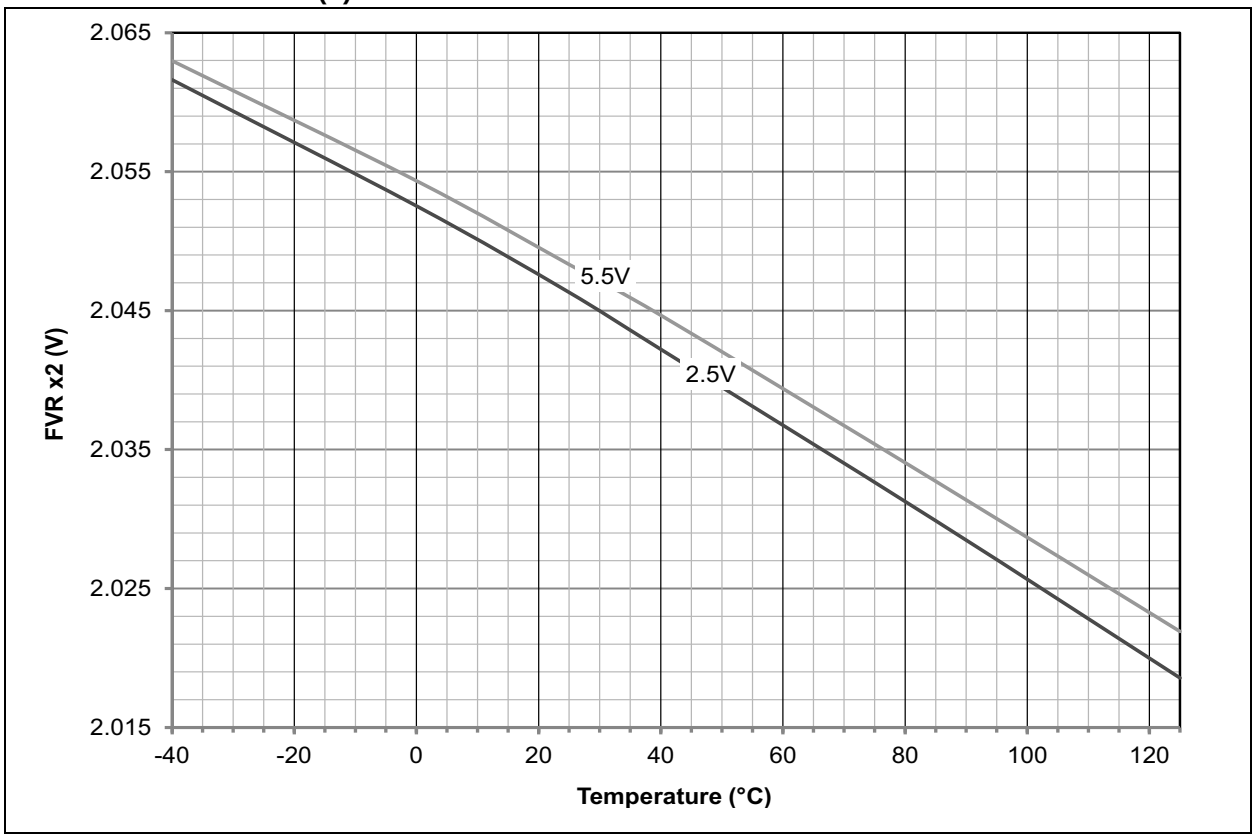
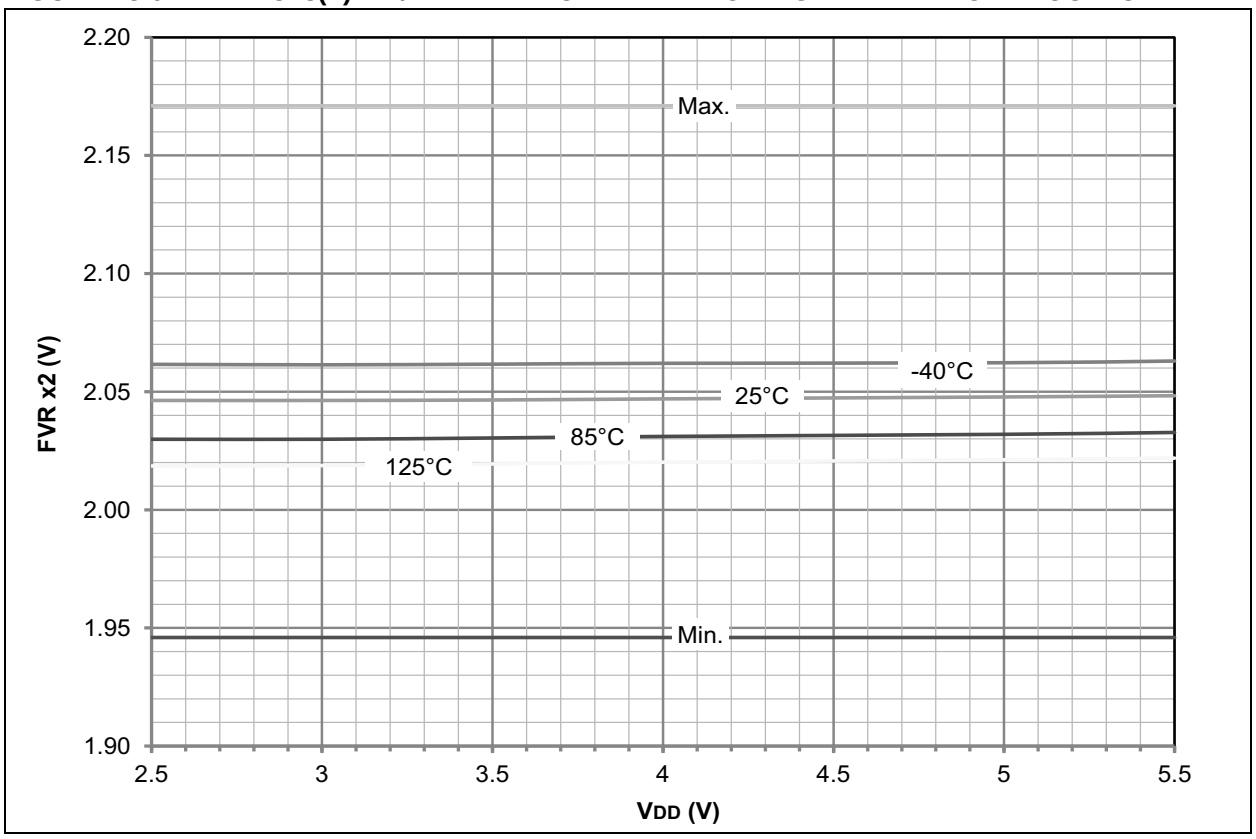
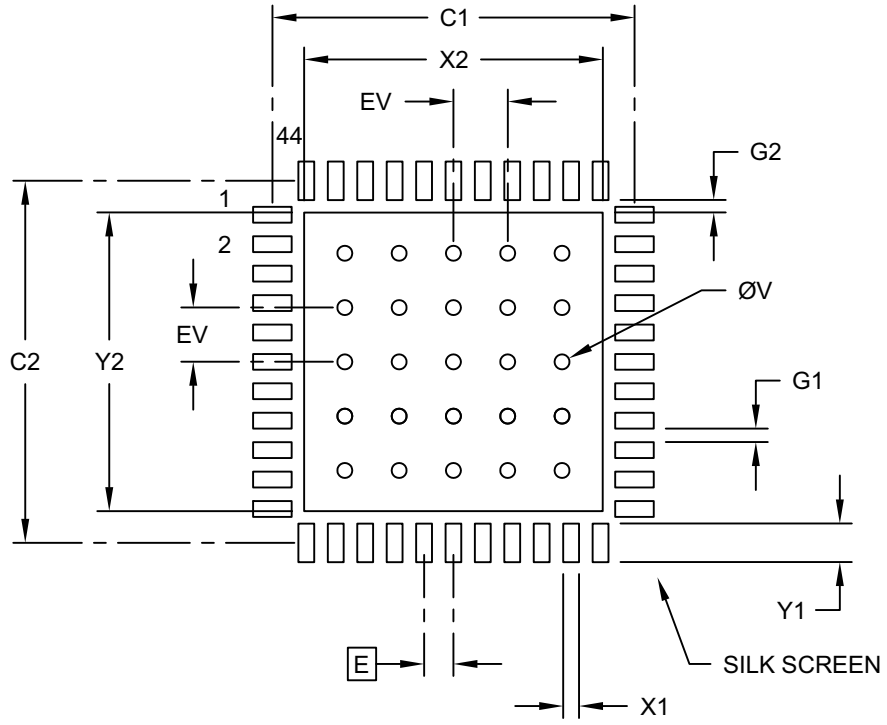


FIGURE 28-97: PIC18(L)F2X/4XK22 TYPICAL FIXED VOLTAGE REFERENCE 2x OUTPUT



44-Lead Plastic Quad Flat, No Lead Package (ML) - 8x8 mm Body [QFN or VQFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.65 BSC	
Optional Center Pad Width	X2			6.60
Optional Center Pad Length	Y2			6.60
Contact Pad Spacing	C1		8.00	
Contact Pad Spacing	C2		8.00	
Contact Pad Width (X44)	X1			0.35
Contact Pad Length (X44)	Y1			0.85
Contact Pad to Contact Pad (X40)	G1	0.30		
Contact Pad to Center Pad (X44)	G2	0.28		
Thermal Via Diameter	V		0.33	
Thermal Via Pitch	EV		1.20	

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

Microchip Technology Drawing No. C04-2103C